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DIALOG(R)File 351:Derwent WPI  
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**Adhesive compsn. having excellent coatability - contg. curing agent  
encapsulated in microcapsule**

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Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 6128545	A	19940510	JP 92280224	A	19921019	199423 B

Priority Applications (No Type Date): JP 92280224 A 19921019

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 6128545	A	7	C09J-163/00		

Abstract (Basic): JP 6128545 A

Adhesive compsn. comprises (A) epoxy resin; and (B) microencapsulated amine cpd. covered with (a) component to be protected and 45-80 wt.% of the amine cpd. is enclosed in the capsule. The thickness of the layer covered is 3-10% of the microcapsule dia. (a) is membrane material made of at least one cpd. of polymethyl methacrylate, polystyrene, ethylene-vinyl acetate copolymer and polyvinyl toluene. Its mol. wt. is 1600-100,000. The amine cpd. is aliphatic polyamine or aromatic polyamine.

USE/ADVANTAGE - The adhesive compsn. has excellent coatability. The microcapsule can be broken not only by pressurising but also by heating, and besides, the concn. of the amine cpd. enclosed is high and the high adhesive strength can be obt'd. at the same deg. as the adhesive strength in the case of the use of the conventional two-component epoxy resin adhesive.

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Derwent Class: A18; A21; A81; G03

International Patent Class (Main): C09J-163/00

International Patent Class (Additional): C08G-059/50; C08L-063/00;  
C09J-011/00